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124-07-F

B-STAGED, EPOXY LAMINATING ADHESIVE FILM

DESCRIPTION: 124-07-F is a B-staged, one part epoxy coating and laminating adhesive film. This system features excellent thermal stability, thermal cycle resistance and chemical resistance. Applications include adhesives, printed circuit board fabrication, advanced material composites, sealing, and high performance coatings. This product is available in thicknesses from 1 to 5 mils (see product codes below). Other thicknesses are available upon request.

GENERAL FILM DESCRIPTION

Substrate Type: PET Release Liner

Product Code	Adhesive Thickness (mils)
124-07-F1	1
124-07-F2	2
124-07-F3	3
124-07-F4	4
124-07-F5	5

TYPICAL CURED PROPERTIES:

Property	Value	Units
Glass Transition Temperature	105	°C
Lap Shear Strength	2100	Psi
Dielectric Strength	425	(volts/mil)
Volume Resistivity	1×10^{16}	Ω - cm
Dielectric Constant	4.0	100 Hz
Useful Temperature Range	-55 to +230	°C
Thermal Stability	Good to 325	°C
Coefficient of Thermal Expansion		
- Below Tg	29.5×10^{-6}	in/in/°C
- Above Tg	13.5×10^{-5}	in/in/°C

CURING GUIDELINES

<u>Temperature (°C)</u>	<u>Time (min.)</u>
150	60
175	30
200	15

These temperatures and times are presented as a guide only. The end-user is encouraged to experiment to determine optimum curing schedule.

HANDLING AND STORAGE

This product is shipped frozen and should be stored frozen to optimize shelf life. **Care should be taken in handling frozen/cold sheets, they are more likely to crack at this point (avoid flexing film if stored at -40°C). Allow material to warm to room temperature before handling.** Please refer to Applying/Transfer Procedure for more details.

SHELF LIFE

6 months at -10°C.

APPLYING/TRANSFER PROCEDURE

To ensure a good bond, the bonding surfaces should be free of any contaminants such as oils, greases, fingerprints, etc.

1. Remove the film from cold storage and allow it to warm to room temperature.
2. After the film has been warmed to room temperature, remove release liner from one side.
3. Preheat substrate to 50°C to 70°C.
4. Locate the adhesive onto the preheated substrate. Smooth out any trapped air by hand, with a roller or any other smoothing device. Some pressure is advisable to ensure intimate contact between the adhesive and substrate.
5. Allow the substrate to cool to room temperature (cooler is better) and remove release liner. This is very important to allow for easy and clean separation of the final release liner from the adhesive.
6. Place the two substrates to be bonded together under uniform pressure. It is advisable to preheat the device(s) being used to apply pressure. An unheated device will result in longer cure times and less uniformity of cure.
7. Cure at the desired cure schedule. Refer to the cure schedules above for guide information.

All technical information is based on data obtained by CMI personnel and is believed to be reliable. No warranty is either expressed or implied with respect to results or possible infringements on patents.

REVISION DATE: 9/11/08 REVISION: B